



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C360GDCNCNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 36pF, 200V, ±2%, C0G, 0805

## A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>360</u> <u>G</u> <u>D</u> <u>C</u> <u>N</u> <u>C</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor			
2	Size	0805 (inch code)	L: 2.0 ± 0.1 mm	W: 1.25 ± 0.1	mm
(3)	Dielectric	C0G	Inner electrode	Ni	
1	Capacitance	<b>36</b> pF	Termination	Cu	
⑤	Capacitance	±2 %	Plating	Sn 100%	(Pb Free)
	tolerance		Product	High-Q	
6	Rated Voltage	200 V	Special	Reserved for	future use
7	Thickness	$0.85 \pm 0.1$ mm	① Packaging	aging Cardboard Type, 7" reel	

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition			
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms			
Q	1000 min				
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.			
Resistance	Whichever is Smaller				
Appearance	No abnormal exterior appearance	Microscope (×10)			
Withstanding	No dielectric breakdown or	200% of the rated voltage			
Voltage	mechanical breakdown				
Temperature	COG				
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)				
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change :	Bending to the limit (1mm)			
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.			
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder			
	is to be soldered newly	245±5℃, 3±0.3sec.			
		(preheating : 80~120℃ for 10~30sec.)			
Resistance to Capacitance change :		Solder pot : 270±5℃, 10±1sec.			
Soldering heat	within ±2.5% or ±0.25pF whichever is larger				
	Tan δ, IR : initial spec.				

	Performance	Test condition	
Vibration Test	Capacitance change :	Amplitude : 1.5mm	
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)	
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)	
Moisture	Capacitance change :	With rated voltage	
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs	
	Q: 200 min		
	IR: 500Mohm or 25Mohm $\cdot \mu$ F		
	Whichever is Smaller		
High Temperature	Capacitance change :	With 200% of the rated voltage	
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature	
	Q: 350 min	1000+48/-0hrs	
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F		
	Whichever is Smaller		
Temperature	Capacitance change :	1 cycle condition	
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25°C	
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C	
		5 cycle test	

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.